## Build Up HDI (Standard)

HDI10_3+4b+3_1,40_35_engl

**10 - Layers**

Core: 0,51 mm Cu 35/35 µm

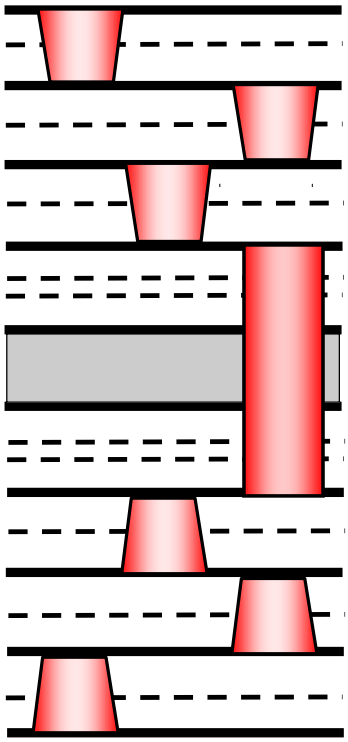
**WE-Articel No.:**

**3 + 4B + 3**

**Customer:**

WÜRTH ELEKTRONIK

vorl. nur CBT Schopfheim

| layer description | | configuration | Raw-Material | CU | PREPREG | Final Thickness | Customer requirements |
|---|---|---|---|---|---|---|---|
| Customer | WE | | | | | [µm] | [µm] |
| | TOP/VS |  | Foil | 12 µm | 1) | 12 | |
| | | | | | 1 x 1080 | 60 | |
| | 2 | | Foil | 12 µm | | 30 | |
| | | | | | 1 x 1080 | 60 | |
| | 3 | | Foil | 12 µm | | 30 | |
| | | | | | 1 x 1080 | 60 | |
| | 4 | | Foil | 12 µm | | 35 | |
| | | | | | 2 x 1080 | 133 | |
| | 5 | | | 35 µm | | 33 | |
| | | | 0,510 mm | | | 510 | |
| | 6 | | | 35 µm | | 33 | |
| | | | | | 2 x 1080 | 133 | |
| | 7 | | Foil | 12 µm | | 35 | |
| | | | | | 1 x 1080 | 60 | |
| | 8 | | Foil | 12 µm | | 30 | |
| | | | | | 1 x 1080 | 60 | |
| | 9 | | Foil | 12 µm | | 30 | |
| | | | | | 1 x 1080 | 60 | |
| | BOT/RS | | Foil | 12 µm | 1) | 12 | |

1) copper thickness outer layers: appr. 55 µm

total material thickness: 1416

Note: Lamination thickness for Prepregs depending on layout characteristics.

| | | | | | | | Date: | Engineer: |
|---|---|---|---|---|---|---|---|---|
| **final lamination thickness:** | **1,42** | +/- | 0,12 | mm | | | | |
| thickness with electro plated Cu: | 1,51 | +/- | 0,15 | mm | | | | |
| total thickness with soldermask | 1,57 | +/- | 0,17 | mm | | | | |
| customer requirement | | +/- | | mm | point: | | | |

| prepared: on | by | checked: on | by | approved: on | by | revision | page: |
|---|---|---|---|---|---|---|---|
| 28.03.2006 | **S. Keller** | 04.05.2006 | M.Kress | 04.05.2006 | R.Schönholz | 00 | 22- |